

● General Description

This silicon carbide Power MOSFET device has been developed using ZMJ's advanced 2nd generation SiC MOSFET technology. The device features a very low $R_{DS(on)}$ over the entire temperature range combined with low capacitances and very high switching operations. It improves application performance in frequency, energy efficiency, system size and weight reduction.

● Features

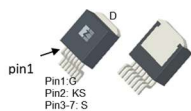
- High blocking voltage
- High speed switching with low capacitances
- Low $R_{DS(on)}$ to minimize conductive loss
- Low gate charge for fast switching
- Low thermal resistance
- 100% avalanche tested
- AEC-Q101 qualified

● Application

- Motor drives
- On board charger
- DC-DC
- Auxiliary drives



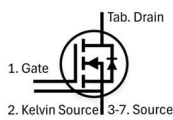
● Product Summary



TO-263-7

● Ordering Information

Part NO.	ZMCSA040R120B7
Marking	ZMCS040R120
Packing information	REEL TAPE
Basic ordering unit (pcs)	1000


 $V_{DS}=1200V$
 $R_{DS(ON)}=39mR$
 $I_D=49A$


● Absolute Maximum Ratings ($T_A=25^{\circ}C$, unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Max.	Unit
Drain-source voltage	V_{DS}		-	1200	V
Gate-source voltage ^①	V_{GS}	Transient Voltage	-10	25	V
	V_{GS}	Static Voltage	-10	24	V
Recommended turn on gate voltage	$V_{GS(on)}$		15	18	V
Recommended turn off gate voltage	$V_{GS(off)}$		-4	0	V
Continuous drain current	I_D	$V_{GS}=18V, T_C=25^{\circ}C$	-	49	A
	I_D	$V_{GS}=18V, T_C=75^{\circ}C$	-	40	A
	I_D	$V_{GS}=18V, T_C=100^{\circ}C$	-	35	A
Pulsed drain current	I_{DM}	Pulsed; $t_p \leq 10 \mu s$; $T_C = 25^{\circ}C$;	-	196	A

Diode continuous current	I_S	$V_{GS}=-4V, T_C=25^{\circ}C$	-	48	A
Diode pulsed current	$I_{S,pulse}$	$V_{GS}=-4V, Pulsed, t_p \leq 10 \mu s, T_C = 25^{\circ}C$	-	192	A
Total power dissipation	P_D	$T_C=25^{\circ}C$	-	238	W
Total power dissipation	P_D	$T_A=25^{\circ}C$	-	3.8	W
Operating junction temperature	T_J		-55	175	$^{\circ}C$
Storage temperature	T_{STG}		-55	175	$^{\circ}C$
Single pulse avalanche energy	E_{AS}	$L=0.5mH, V_{GS}=18V, R_g=25\Omega,$	-	588	mJ

● Thermal resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	R_{thJC}	-	-	0.68	$^{\circ}C/W$
Thermal resistance, junction - ambient	$R_{thJA}^{(2)}$	-	-	40	$^{\circ}C/W$
Soldering temperature	T_{sold}	-	-	260	$^{\circ}C$

● Electronic Characteristics ($T_J=25^{\circ}C$, unless otherwise specified)

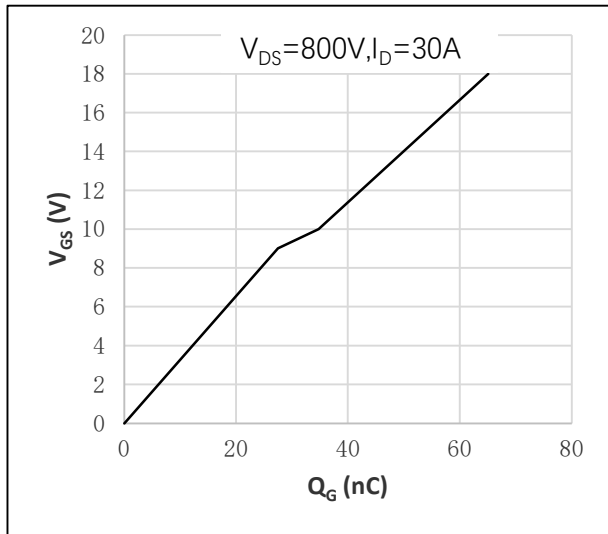
Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Drain-source breakdown voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	1200	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=5mA$	2	2.8	4	V
Drain-source leakage current	I_{DSS}	$V_{GS}=0V, V_{DS}=1200V$	-	-	10	μA
Gate- source leakage current	I_{GSS}	$V_{GS}=-10V, V_{DS}=0V$	-	-	-100	nA
		$V_{GS}=25V, V_{DS}=0V$	-	-	100	nA
Static drain-source on resistance	$R_{DS(ON)}$	$V_{GS}=18V, I_D=30A, T_J=25^{\circ}C$	-	39	47	m Ω
		$V_{GS}=18V, I_D=30A, T_J=175^{\circ}C$	-	78	-	m Ω
		$V_{GS}=15V, I_D=30A, T_J=25^{\circ}C$	-	47	-	m Ω
Forward transconductance	g_{FS}	$V_{DS}=10V, I_{SD}=30A$	-	7.5	-	S
Diode forward voltage	V_{FSD}	$V_{GS}=-4V, I_{SD}=30A$	-	4.4	5	V

● Dynamic characteristics ($T_J=25^{\circ}C$, unless otherwise specified)

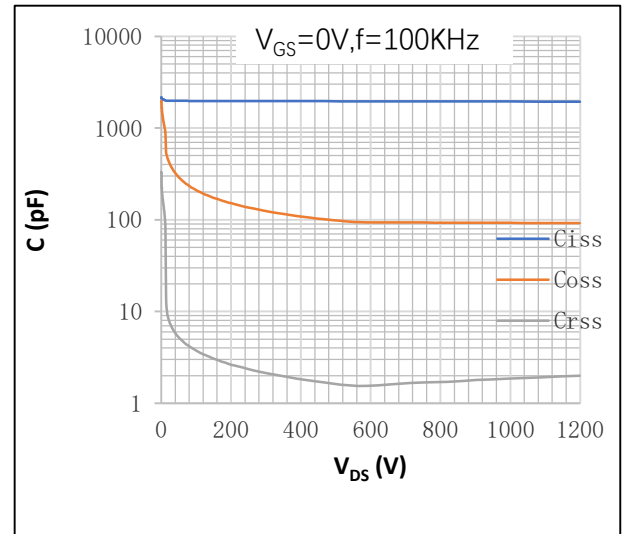
Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Input capacitance	C_{iss}	$f=100KHz, V_{DS}=800V, V_{GS}=0V$	-	2061	-	pF
Output capacitance	C_{oss}		-	94	-	pF
Reverse transfer capacitance	C_{rss}		-	1.6	-	pF
Output charge	Q_{oss}	$f=100KHz, V_{GS}=0V,$	-	123.3	-	nC

Coss stored energy	E_{oss}	$V_{DS}=0V$ to 800V	-	34.5	-	uJ
Gate resistance	R_g	$f = 1MHz$	-	1.4	-	Ω
Total gate charge	Q_g	$V_{DD} = 800V,$ $I_D = 30A,$ $V_{GS} = -4V/18V$	-	65.1	-	nC
Gate-source charge	Q_{gs}		-	27.5	-	nC
Gate-drain charge	Q_{gd}		-	7.3	-	nC
Turn-on delay time	$t_{D(on)}$		-	32	-	ns
Turn-on rise time	t_r	$V_{GS}=-4V/18V,$ $V_{DS}=800V,$ $R_G = 30\Omega,$ $I_D = 20A,$ $L=200uH$	-	20	-	ns
Turn-off delay time	$t_{D(off)}$		-	79	-	ns
Turn-off fall time	t_f		-	13	-	ns
Turn-on energy	E_{on}		-	356	-	uJ
Turn-off energy	E_{off}		-	286	-	uJ
Reverse recovery time	t_{rr}	$V_{DD}=800V, dI_S/dt =$ $890A/us, I_S=20A$	-	36	-	ns
Reverse recovery charge	Q_{rr}		-	223	-	nC

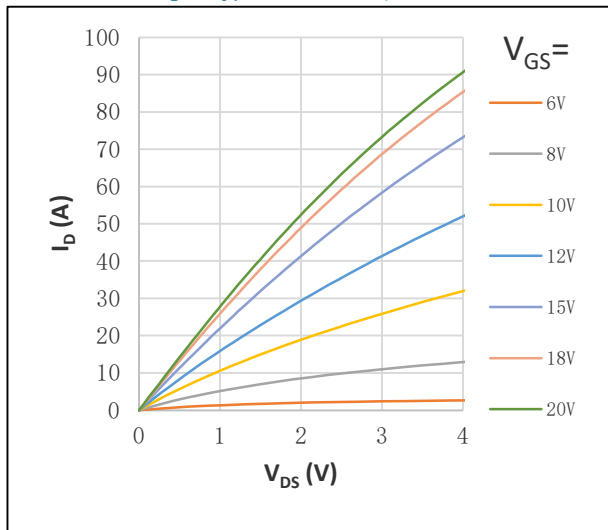
● Fig.1 Gate-source voltage as a function of gate charge; Typical values; $T_j=25^\circ\text{C}$



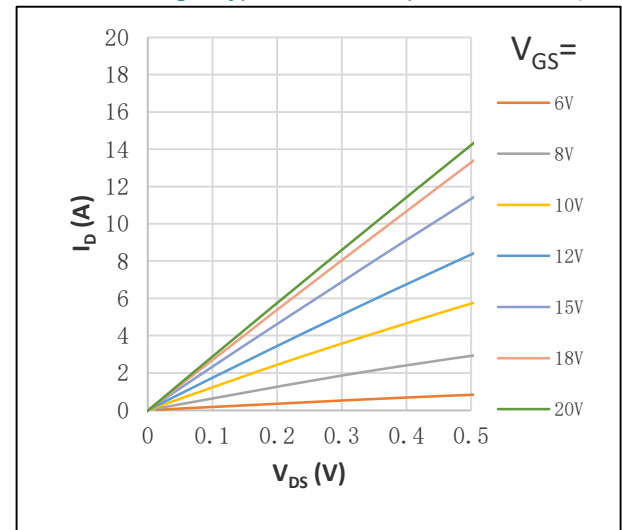
● Fig.2 Input, output and reverse transfer capacitances as a function of drain-source voltage; Typical values; $T_j=25^\circ\text{C}$



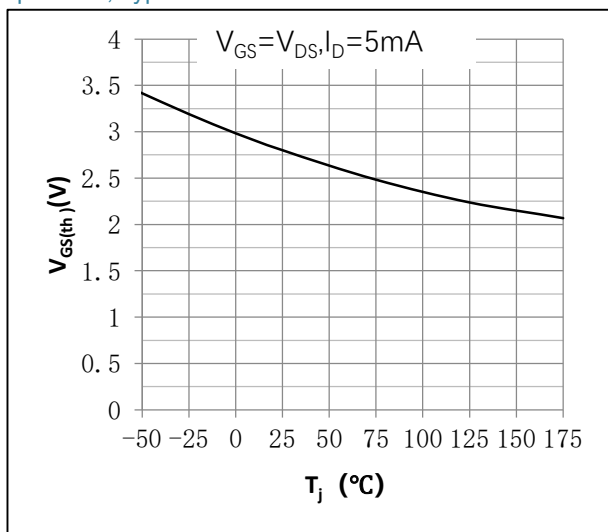
● Fig.3 Output characteristics: drain current as a function of drain-source voltage; Typical values; $T_j=25^\circ\text{C}$



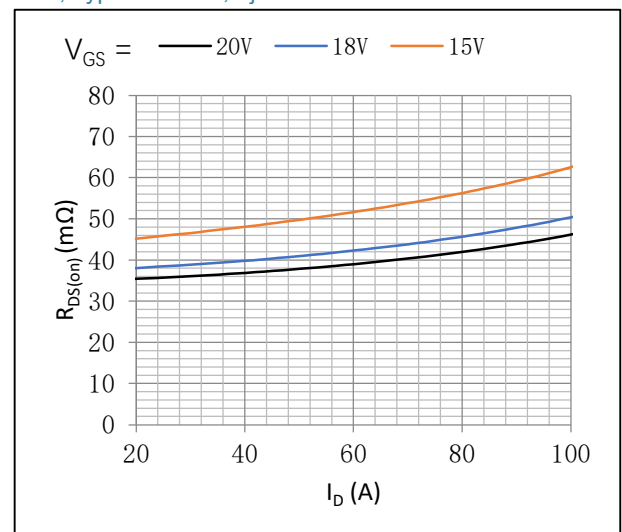
● Fig.4 Output characteristics: drain current as a function of drain-source voltage; Typical values: Expanded curve; $T_j=25^\circ\text{C}$



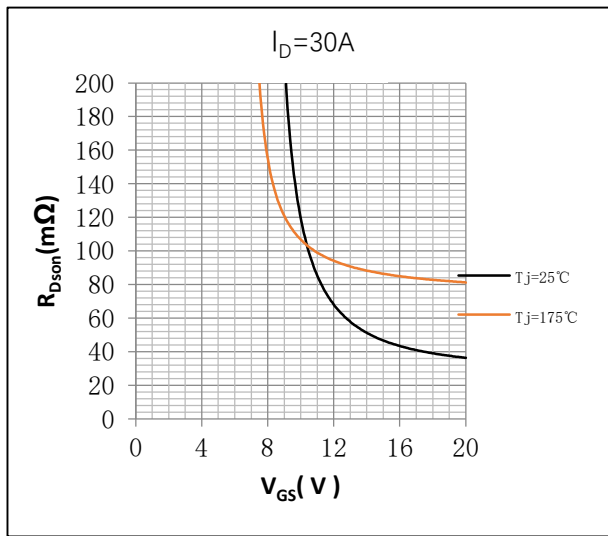
● Fig.5 Gate-source threshold voltage as a function of junction temperature; Typical values



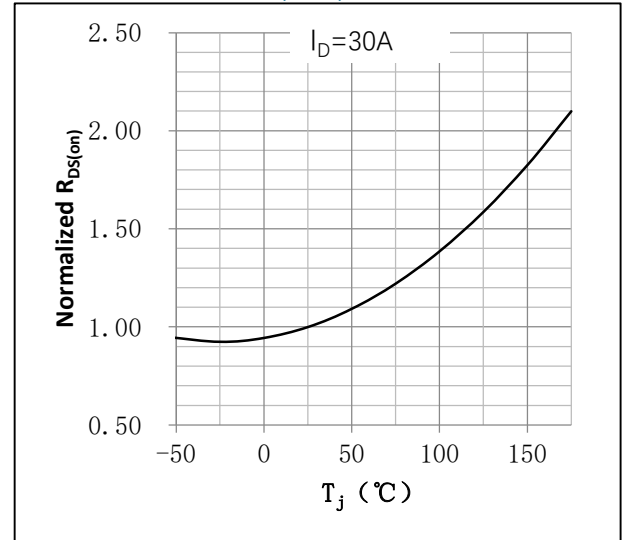
● Fig.6 Drain-source on-state resistance as a function of drain current; Typical values; $T_j=25^\circ\text{C}$



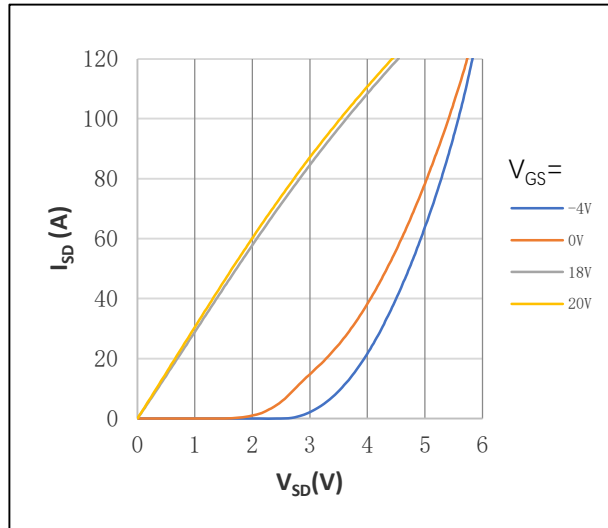
● Fig.7 Drain-source on-state resistance as a function of gate-source voltage; Typical values



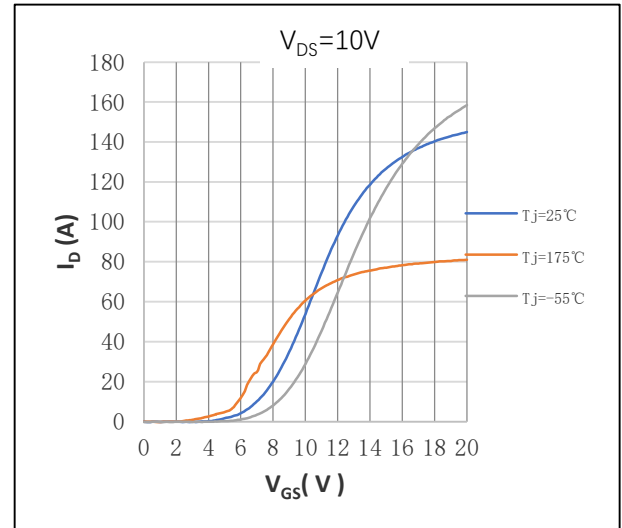
● Fig.8 Normalized drain-source on-state resistance factor as a function of junction temperature; Typical values Normalized On-Resistance = $R_{DS(on)}/R_{DS(on)}(25^{\circ}\text{C})$



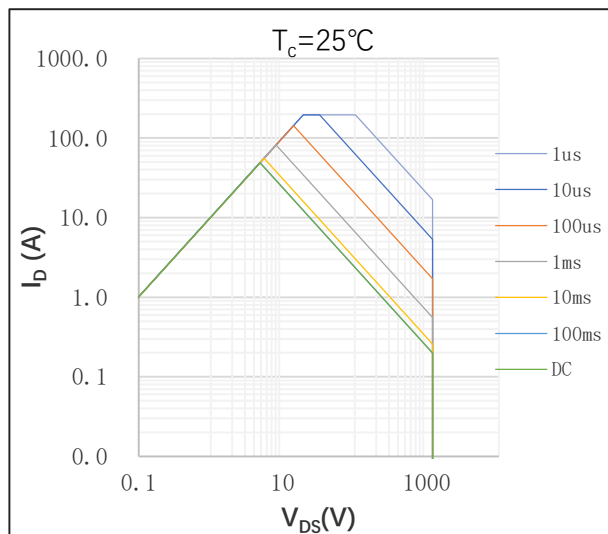
● Figure 9. Source (diode forward) current as a function of source-drain (diode forward) voltage; Typical values; $T_J = 25^{\circ}\text{C}$



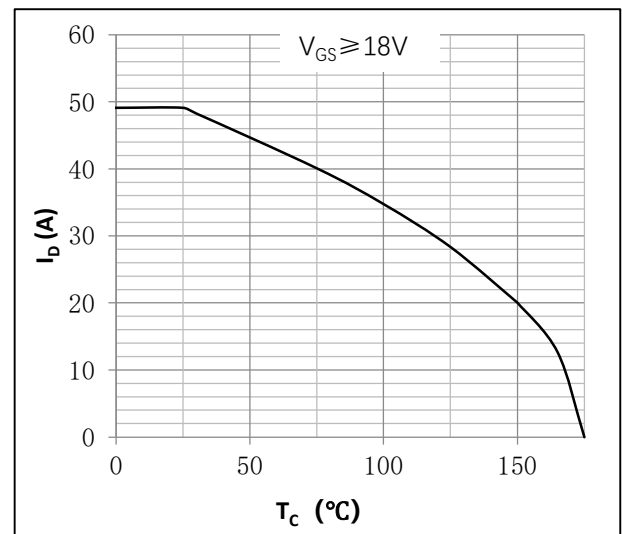
● Figure 10. Transfer characteristics: drain current as a function of gate-source voltage; Typical values



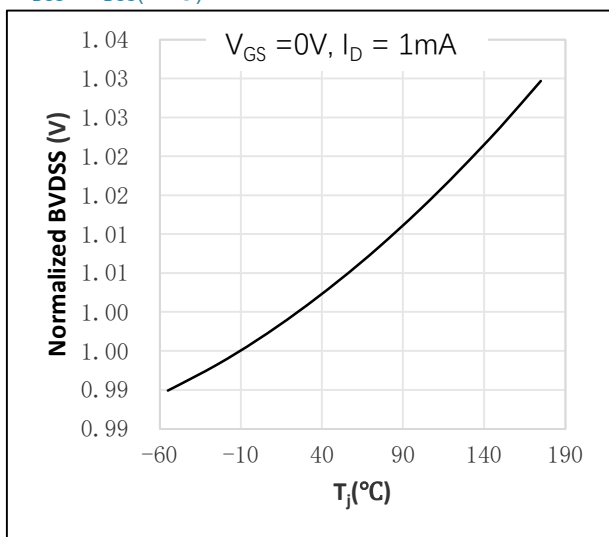
● Fig.11 Safe operating area: continuous and peak drain currents as a function of drain-source voltage; Calculative values



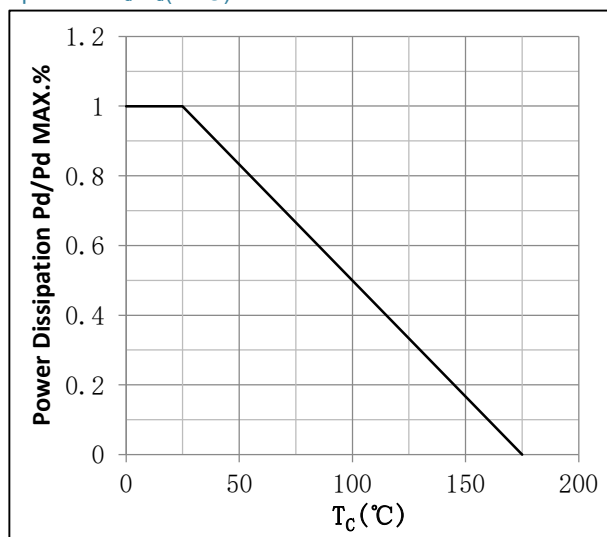
● Fig.12 Continuous drain current as a function of case temperature³; Calculative values



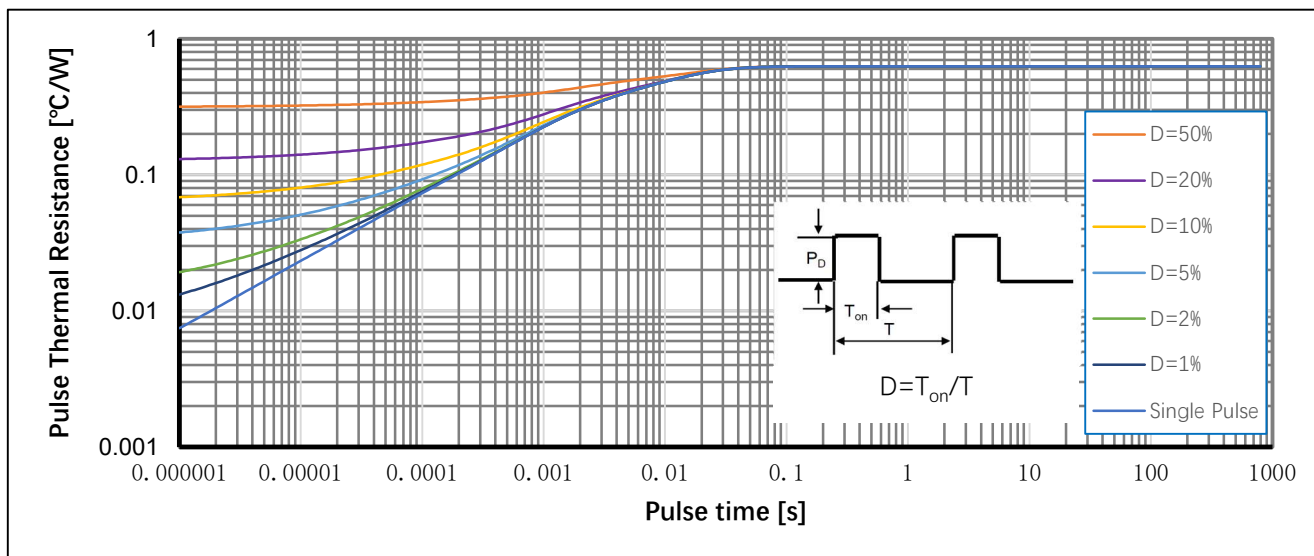
● Fig.13 Drain-source breakdown voltage as a function of junction temperature; Typical values Normalized $BV_{DSS} = BV_{DSS}/BV_{DSS}(25^{\circ}\text{C})$



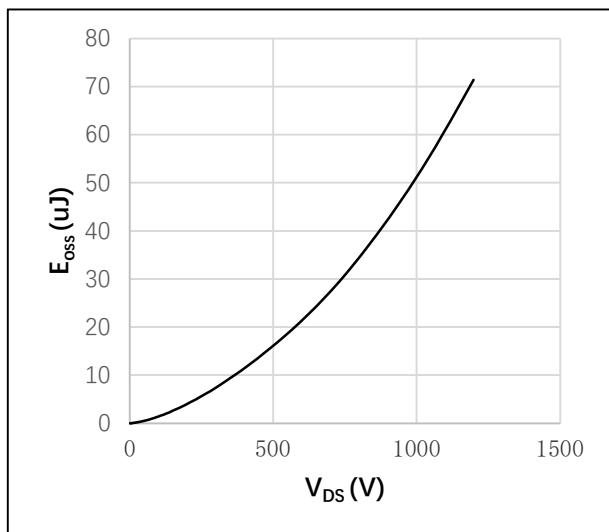
● Fig.14 Normalized total power dissipation as a function of case temperature; Calculative values Normalized Power Dissipation $= P_d/P_d(25^{\circ}\text{C})$



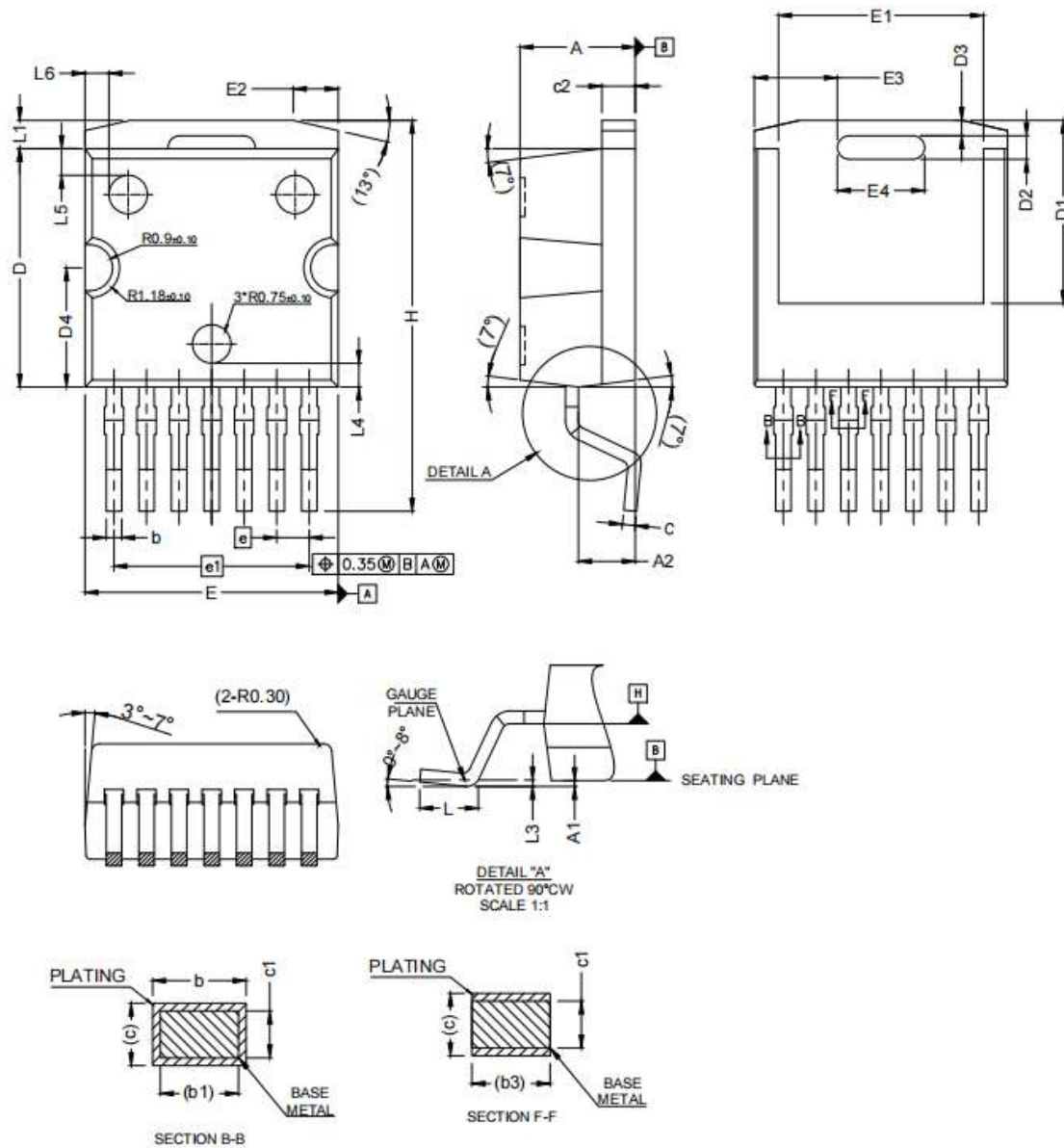
● Fig.15 Transient thermal impedance from junction to case as a function of pulse duration; max values



● Fig.16 Output capacitor stored energy as a function of drain-source voltage; Typical values; $T_J = 25^{\circ}\text{C}$



● Package Outline



SYMBOL	MIN	MAX	SYMBOL	MIN	MAX
A	4.30	4.70	L	1.78	2.79
A1	-	0.25	L1	-	1.60
A2	2.02	2.42	L3	0.25BSC	
b	0.50	0.70	L4	0.93BSC	
b1	0.50	0.65	L5	1.04BSC	
b3	0.60	0.75	L6	0.93BSC	
c	0.45	0.60	H	14.61	15.88
c1	0.45	0.55			
c2	1.25	1.40			
D	9.10	9.50			
D1	6.86	7.42			
D2	0.72	1.12			
D3	0.40	0.80			
D4	4.45	4.85			
E	9.68	10.08			
E1	7.70	8.30			
E2	1.55	1.95			
E3	3.04	3.44			
E4	3.21	3.61			
e	1.27 BSC				
e1	7.62 BSC				

● Note

- ① Pulse : $V_{GS}=+25V/-10V$, Duty cycle=50%, $T_J=175^{\circ}C$, $t=1000$ hours; For DC, the following test conditions can be passed: $V_{GS}=+24V/-10V$, $T_J=175^{\circ}C$, $t=1000$ hours;
- ② The value of $R_{\theta JA}$ is measured with the device in a still environment with $T_A=25^{\circ}C$;
- ③ Practically the current will be limited by PCB, thermal design and operating temperature. $V_{GS}=18V$.

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● Revision History

Version	Date	Change
A	2025/5/18	New